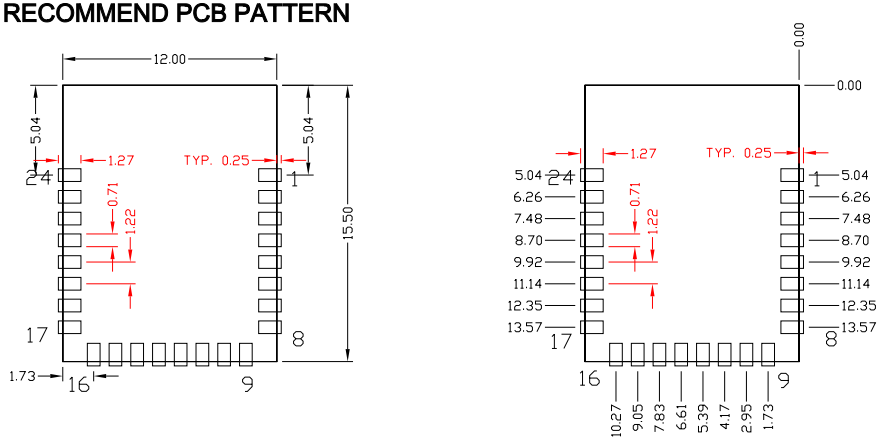
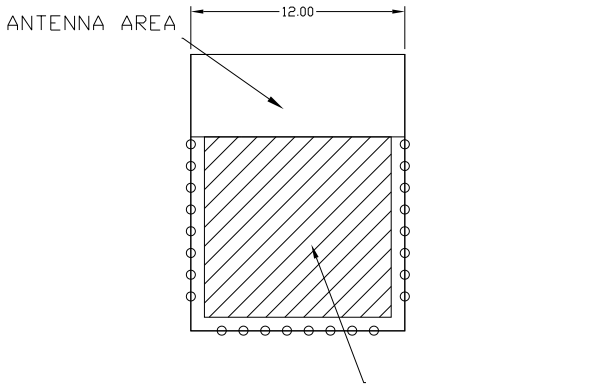
REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
0.1	INITIAL RELEASE	WW1711	

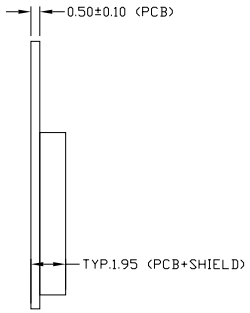
RECOMMEND PCB PATTERN

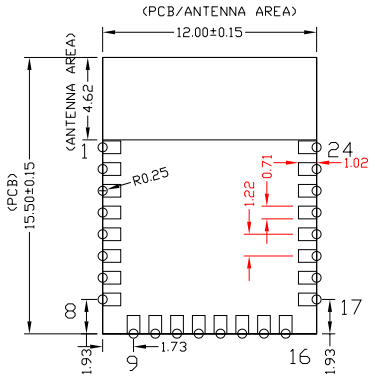


MODULE PAD ASSIGNMENT:

PAD1:P0/P34
PAD2:I2C_SCL
PAD3:XRES
PAD4:I2C_SDA
PAD5:P2/P37/P28
PAD6:SPI2_CS_N
PAD7:GND
PAD8:SPI2_MISO
PAD9:SPI2_MOSI
PAD10:SPI2_CLK
PAD11:GPIO_0
PAD12:GPIO_1
PAD13:GND
PAD14:GPIO_4
PAD15:P4/P24
PAD16:UART_TXD
PAD17:UART_CTS
PAD18:UART_RTS
PAD19:GPIO_7
PAD20:UART_RXD
PAD21:VDDIN
PAD22:GPIO_3
PAD23:GPIO_6
PAD24:GND







SEEN FROM TOP

SEEN FROM SIDE

SEEN FROM BOTTOM



SCALE 1:1

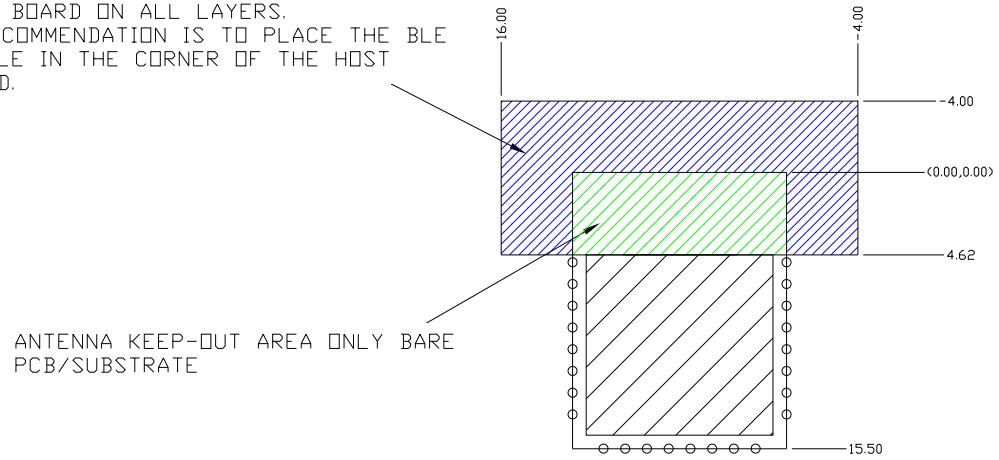
UNLESS OTHERWISE SPECIFIED	SIGNATURES	DATE	CYPRESS SEMICONDUCTOR Corp.
DIMENSIONS ARE IN MM TOLERANCES ON: +/- 0.15 MM ANGLES +/-0.5 DEGREE	DRAWN: Janey Tang	WW1711	CYBT-343026-01
	CHECKED		
	ENGRG		
	ISSUED		

SIZE	REV NO	DWG NO
	0.1	

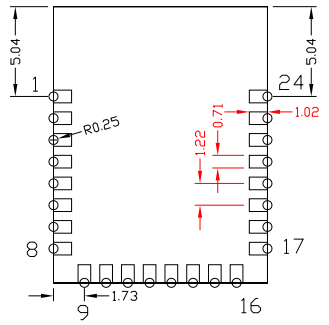
SCALE 5:1 | THE 3RD PROJECTION | SHEET: 1 OF 1

HOST PCB KEEP OUT AREA AROUND ANTENNA

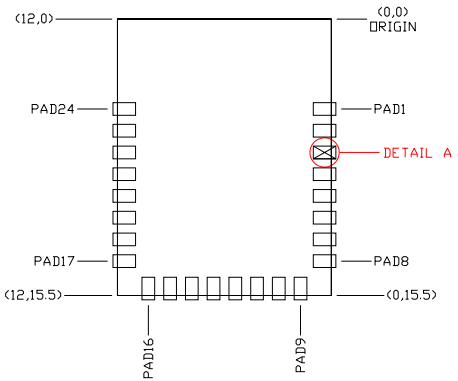
1. FOR BEST RF PERFORMANCE,ADDITIONAL KEEPOUT IN BLUE HATCHED AREA ON THE HOST BOARD ON ALL LAYERS.
2. RECOMMENDATION IS TO PLACE THE BLE MODULE IN THE CORNER OF THE HOST BOARD.

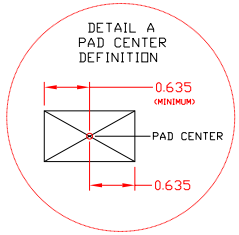


PAD DIMENSIONS



SOLDER PAD AND LOCATION





Solder Pad (Center of Pad)	Location (X,Y) from Origin (mm)	Dimension from Origin (mil)
1	(0.38, 5.04)	(14.96, 198.42)
2	(0.38, 6.26)	(14.96, 246.46)
3	(0.38, 7.48)	(14.96, 294.49)
4	(0.38, 8.70)	(14.96, 342.52)
5	(0.38, 9.92)	(14.96, 390.55)
6	(0.38, 11.14)	(14.96, 438.58)
7	(0.38, 12.35)	(14.96, 486.22)
8	(0.38, 13.57)	(14.96, 534.25)
9	(1.73,15.11)	(68.11, 594.88)
10	(2.95,15.11)	(116.14, 594.88)
11	(4.17,15.11)	(164.17, 594.88)
12	(5.39,15.11)	(212.20, 594.88)
13	(6.61,15.11)	(260.24, 594.88)
14	(7.83,15.11)	(308.27, 594.88)
15	(9.05,15.11)	(356.30, 594.88)
16	(10.27,15.11)	(404.33, 594.88)
17	(11.62,13.57)	(457.48, 534.25)
18	(11.62,12.35)	(457.48, 486.22)
19	(11.62,11.14)	(457.48, 438.58)
20	(11.62,9.92)	(457.48, 390.55)
21	(11.62,8.70)	(457.48, 342.52)
22	(11.62,7.48)	(457.48, 294.49)
23	(11.62,6.26)	(457.48, 246.46)
24	(11.62,5.04)	(457.48, 198.42)

UNLESS OTHERWISE SPECIFIED	SIGNATURES	DATE	
DIMENSIONS ARE IN MM TOLERANCES ON: +/- 0.20 MM	DRAWN: Janey Tang	WW1711	CYPRESS SEMICONDUCTOR Corp.
	CHECKED		
	ENGRG		
ANGLES +/-0.5 DEGREE	ISSUED		CYBT-343026-01
			SIZE: REV NO 0.1 / DWG NO
			SCALE 5:1 / THE 3RD PROJECTION / SHEET: 2 OF 2